



Material Content Data Sheet



Sales Product Name		BTS50015-1TAD		Issued		9. January 2019		
MA#		MA004091350						
Package		PG-TO263-7-10		Weight*		1557.30 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	11.254	0.72	0.72	7227	7227
chip_2	inorganic material	silicon	7440-21-3	1.848	0.12	0.12	1186	1186
leadframe	inorganic material	phosphorus	7723-14-0	0.247	0.02		159	
	non noble metal	iron	7439-89-6	0.823	0.05		529	
	non noble metal	copper	7440-50-8	822.375	52.81	52.88	528077	528765
	non noble metal	aluminium	7429-90-5	11.063	0.71	0.71	7104	7104
wire	non noble metal	aluminium	7429-90-5	11.063	0.71	0.71	7104	7104
	organic material	carbon black	1333-86-4	8.345	0.54		5359	
encapsulation	plastics	epoxy resin	-	91.798	5.89		58947	
	inorganic material	silicondioxide	60676-86-0	456.209	29.29	35.72	292947	357253
leadfinish	non noble metal	tin	7440-31-5	12.163	0.78	0.78	7810	7810
plating	inorganic material	phosphorus	7723-14-0	0.007	0.00		5	
	non noble metal	nickel	7440-02-0	2.941	0.19	0.19	1888	1893
solder	non noble metal	tin	7440-31-5	0.145	0.01		93	
	noble metal	silver	7440-22-4	0.182	0.01		117	
	non noble metal	lead	7439-92-1	6.946	0.45	0.47	4460	4670
	plastics	Polyimide	26023-21-2	0.198	0.01	0.01	127	127
glue	plastics	Polyimide	26023-21-2	0.198	0.01	0.01	127	127
heatspreader	inorganic material	phosphorus	7723-14-0	0.039	0.00		25	
	non noble metal	iron	7439-89-6	0.131	0.01		84	
	non noble metal	iron	7439-89-6	0.131	0.01		84	
	non noble metal	copper	7440-50-8	130.589	8.39	8.40	83856	83965
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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